

H11N1M, H11N2M, H11N3M

6-Pin DIP High Speed Logic Optocouplers

Features

- High data rate, 5MHz typical (NRZ)
- Free from latch up and oscillation throughout voltage and temperature ranges.
- Microprocessor compatible drive
- Logic compatible output sinks 16mA at 0.5V maximum
- Guaranteed on/off threshold hysteresis
- Wide supply voltage capability, compatible with all popular logic systems
- High common mode transient immunity, 2000V/μs minimum
- Fast switching $t_r = 7.5\text{ns}$ typical, $t_f = 12\text{ns}$ typical
- Underwriter Laboratory (UL) recognized—file #E90700
- VDE recognized—File#102497 – Add option V (e.g., H11N1VM)

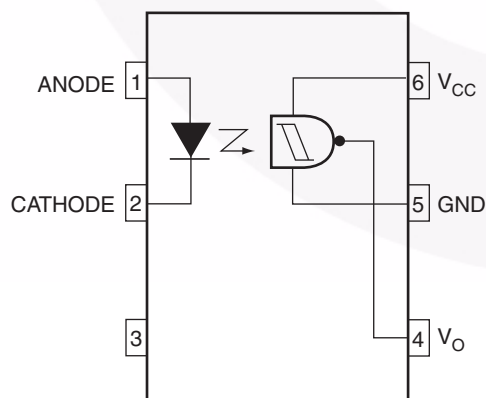
Applications

- Logic to logic isolator
- Programmable current level sensor
- Line receiver—eliminate noise and transient problems
- A.C. to TTL conversion—square wave shaping
- Interfaces computers with peripherals
- Isolated power MOS driver for power supplies

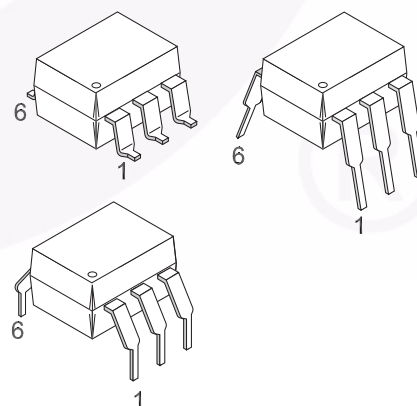
Description

The H11NXM series has a high speed integrated circuit detector optically coupled to an AlGaAs infrared emitting diode. The output incorporates a Schmitt trigger, which provides hysteresis for noise immunity and pulse shaping. The detector circuit is optimized for simplicity of operation and utilizes an open collector output for maximum application flexibility.

Schematic



Package Outlines



Truth Table

Input	Output
H	L
L	H

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise specified.)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Value	Units
TOTAL DEVICE			
T _{STG}	Storage Temperature	-40 to +150	°C
T _{OPR}	Operating Temperature	-40 to +85	°C
T _{SOL}	Lead Solder Temperature	260 for 10 sec	°C
P _D	Total Device Power Dissipation @ 25°C Derate Above 25°C	250	mW
		2.94	mW/°C
EMITTER			
I _F	Continuous Forward Current	30	mA
V _R	Reverse Voltage	6	V
I _{F(pk)}	Forward Current – Peak (1µs pulse, 300 pps)	1.0	A
P _D	LED Power Dissipation 25°C Ambient Derate Linearly From 25°C	120	mW
		1.41	mW/°C
DETECTOR			
P _D	Detector Power Dissipation @ 25°C Derate Linearly from 25°C	150	mW
		1.76	mW/°C
V _O	V ₄₅ Allowed Range	0 to 16	V
V _{CC}	V ₆₅ Allowed Range	0 to 16	V
I _O	I ₄ Output Current	50	mA

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified.)**Individual Component Characteristics**

Symbol	Parameters	Test Conditions	Device	Min.	Typ.*	Max.	Units
EMITTER							
V_F	Input Forward Voltage	$I_F = 10\text{mA}$	All		1.4	2	V
		$I_F = 0.3\text{mA}$		0.75	1.25		
I_R	Reverse Current	$V_R = 5\text{V}$	All			10	μA
C_J	Capacitance	$V = 0, f = 1.0\text{MHz}$	All			100	pF
DETECTOR							
V_{CC}	Operating Voltage Range		All	4		15	V
$I_{CC(\text{off})}$	Supply Current	$I_F = 0, V_{CC} = 5\text{V}$	All		6	10	mA
I_{OH}	Output Current, High	$I_F = 0.3\text{mA}, V_{CC} = V_O = 15\text{V}$	All			100	μA

Transfer Characteristics

Symbol	DC Characteristics	Test Conditions	Device	Min.	Typ.*	Max.	Units
$I_{CC(\text{on})}$	Supply Current	$I_F = 10\text{mA}, V_{CC} = 5\text{V}$	All		6.5	10	mA
V_{OL}	Output Voltage, Low	$R_L = 270\Omega, V_{CC} = 5\text{V}, I_F = I_{F(\text{on})} \text{ max.}$	All			0.5	V
$I_{F(\text{on})}$	Turn-On Threshold Current	$R_L = 270\Omega, V_{CC} = 5\text{V}^{(1)}$	H11N1M	0.8		3.2	mA
			H11N2M	2.3		5	
			H11N3M	4.1		10	
$I_{F(\text{off})}$	Turn-Off Threshold Current	$R_L = 270\Omega, V_{CC} = 5\text{V}$	All	0.3			mA
$I_{F(\text{off})} / I_{F(\text{on})}$	Hysteresis Ratio	$R_L = 270\Omega, V_{CC} = 5\text{V}$	All	0.65		0.95	

Switching Speed

Symbol	AC Characteristics	Test Conditions	Device	Min.	Typ.*	Max.	Units
t_{PHL}	Propagation Delay Time HIGH-to-LOW	$C = 120\text{pF}, t_p = 1\mu\text{s}, R_E = {}^{(2)}$, Figure 1	All		100	330	ns
t_r	Rise Time	$C = 120\text{pF}, t_p = 1\mu\text{s}, R_E = {}^{(2)}$, Figure 1	All		7.5		ns
t_{PLH}	Propagation Delay Time LOW-to-HIGH	$C = 120\text{pF}, t_p = 1\mu\text{s}, R_E = {}^{(2)}$, Figure 1	All		150	330	ns
t_f	Fall Time	$C = 120\text{pF}, t_p = 1\mu\text{s}, R_E = {}^{(2)}$, Figure 1	All		12		ns
	Data Rate		All		5		MHz

Isolation Characteristics

Symbol	Parameters	Test Conditions	Min.	Typ.*	Max.	Units
V_{ISO}	Input-Output Isolation Voltage	$f = 60\text{ Hz}, t = 1\text{ sec.}$	7500			V_{PEAK}
C_{ISO}	Isolation Capacitance	$V_{I-O} = 0\text{V}, f = 1\text{ MHz}$		0.4	0.6	pF
R_{ISO}	Isolation Resistance	$V_{I-O} = \pm 500\text{ VDC}$	10^{11}			Ω

*Typical values at $T_A = 25^\circ\text{C}$ **Notes:**

- Maximum $I_{F(\text{ON})}$ is the maximum current required to trigger the output. For example, a 3.2mA maximum trigger current would require the LED to be driven at a current greater than 3.2mA to guarantee the device will turn on. A 10% guard band is recommended to account for degradation of the LED over its lifetime. The maximum allowable LED drive current is 30mA.
- H11N1: $R_E = 910\Omega$, H11N2: $R_E = 560\Omega$, H11N3: $R_E = 240\Omega$

Typical Performance Curves

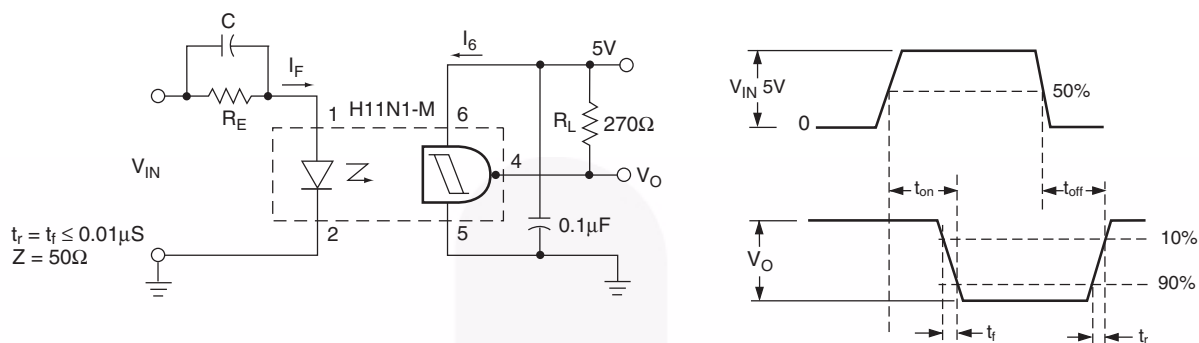


Figure 1. Switching Test Circuit and Waveforms

Figure 2. Transfer Characteristics

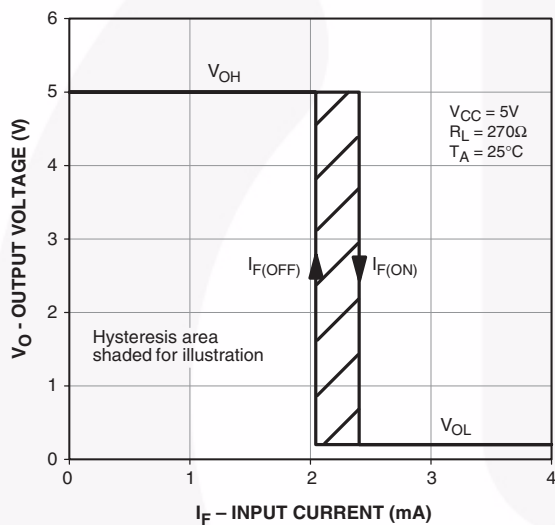


Figure 3. Threshold Current vs. Supply Voltage

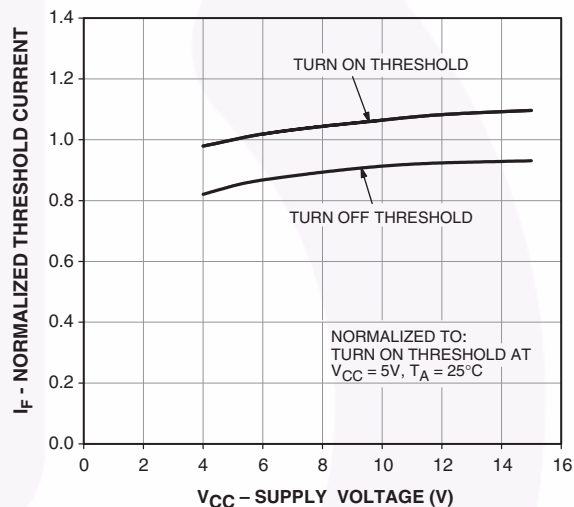


Figure 4. Threshold Current vs. Temperature

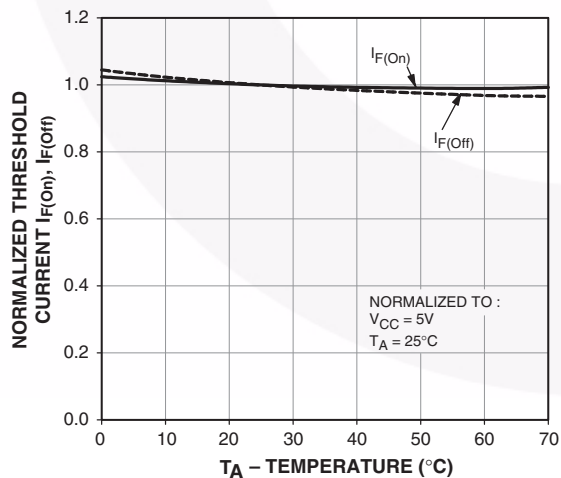
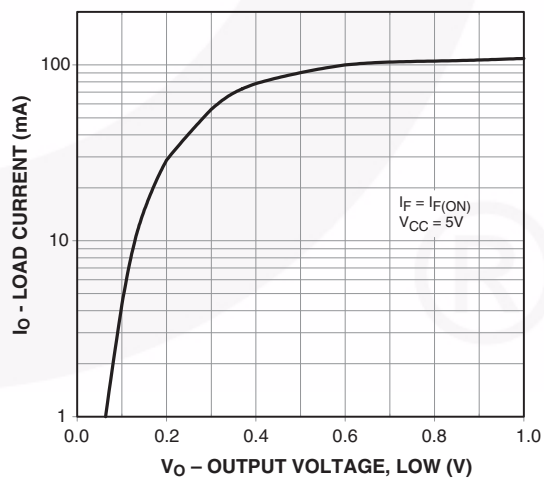


Figure 5. Load Current vs. Output Voltage



Typical Performance Curves (Continued)

Figure 6. Supply Current vs. Supply Voltage

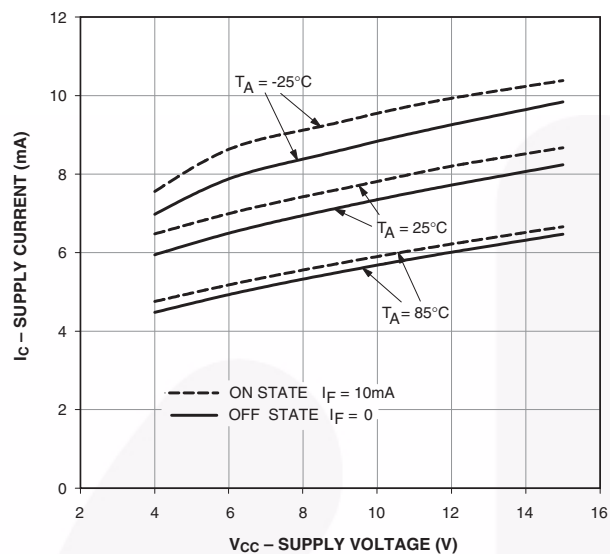
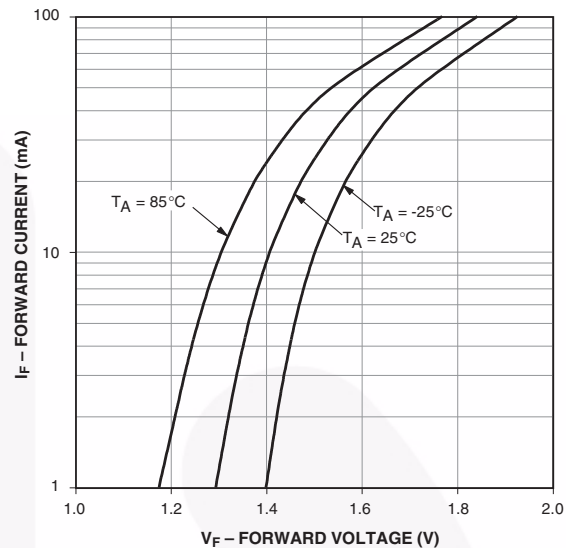
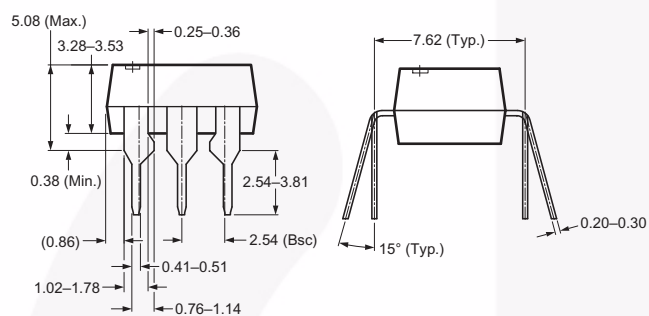
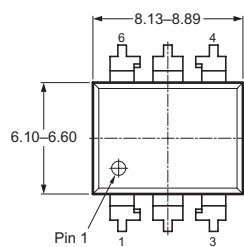


Figure 7. LED Forward Voltage vs. Forward Current

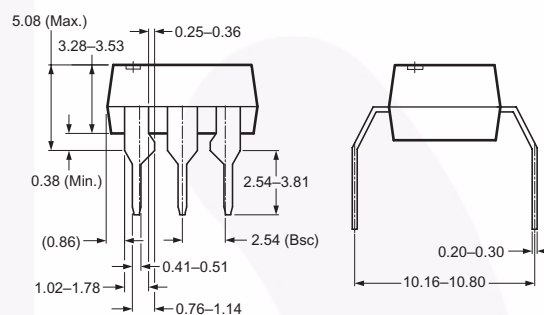
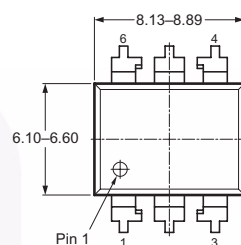


Package Dimensions

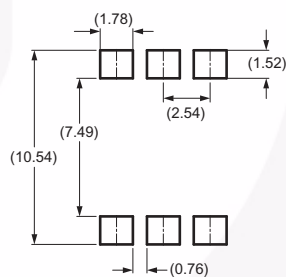
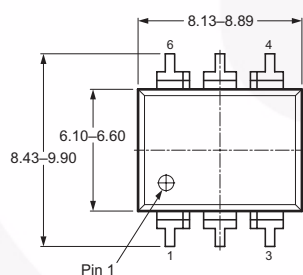
Through Hole



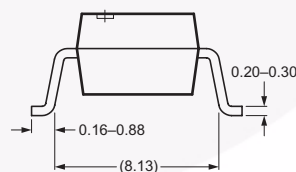
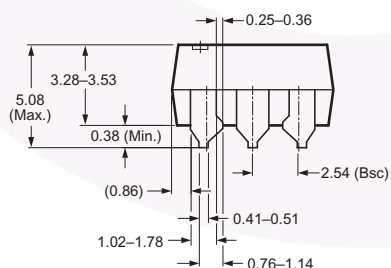
0.4" Lead Spacing



Surface Mount



Recommended Pad Layout

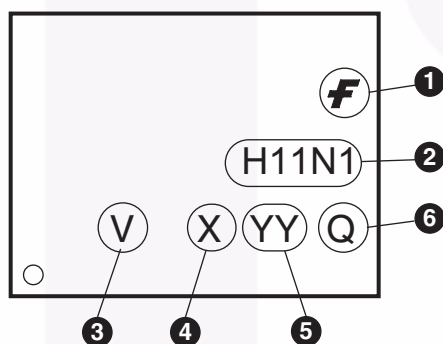


Note:
All dimensions in mm.

Ordering Information

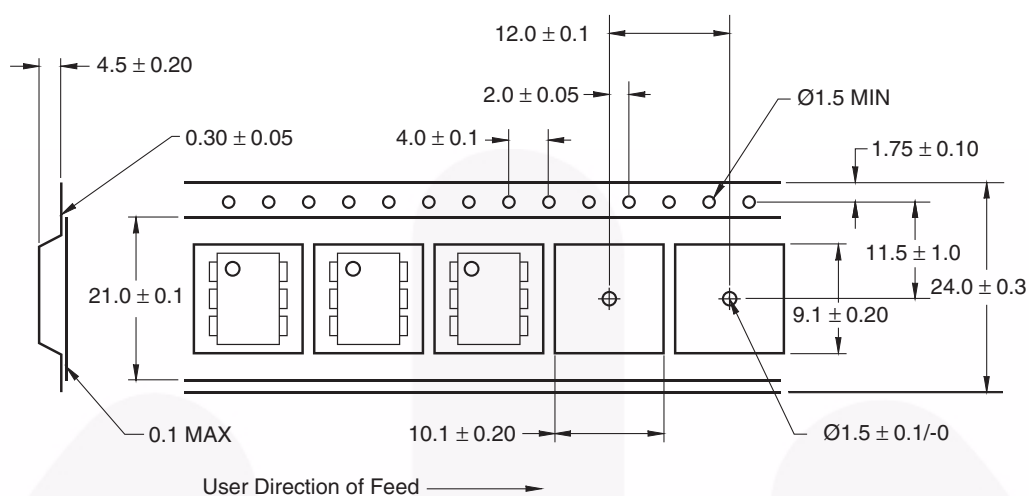
Option	Order Entry Identifier (Example)	Description
No option	H11N1M	Standard Through Hole Device
S	H11N1SM	Surface Mount Lead Bend
SR2	H11N1SR2M	Surface Mount; Tape and Reel
T	H11N1TM	0.4" Lead Spacing
V	H11N1VM	VDE 0884
TV	H11N1TVM	VDE 0884, 0.4" Lead Spacing
SV	H11N1SVM	VDE 0884, Surface Mount
SR2V	H11N1SR2VM	VDE 0884, Surface Mount, Tape and Reel

Marking Information

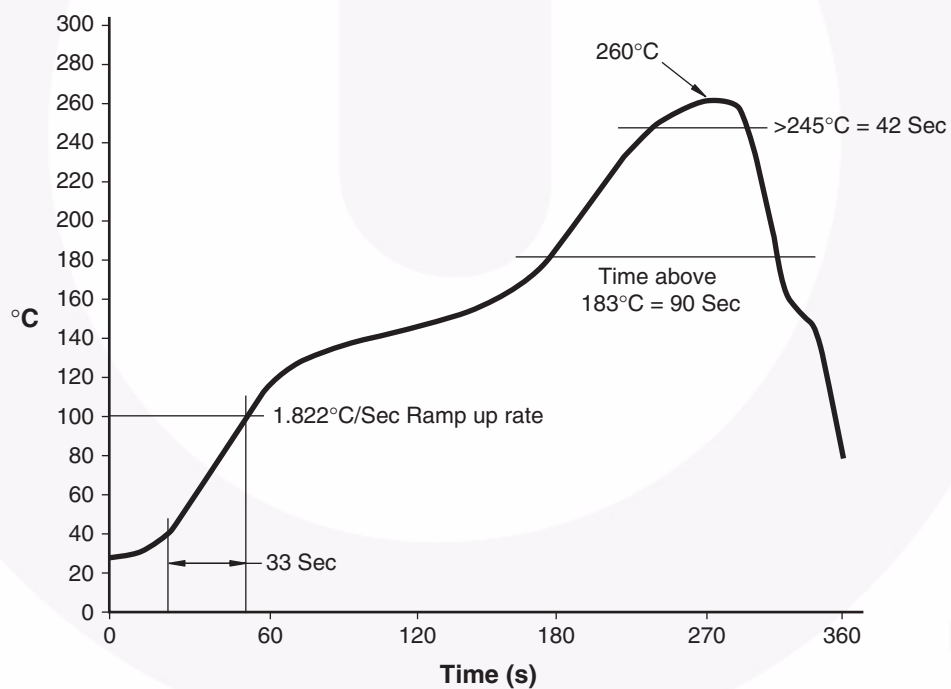


Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code, e.g., '3'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

*Note – Parts that do not have the 'V' option (see definition 3 above) that are marked with date code '325' or earlier are marked in portrait format.







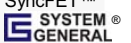
All dimensions are in millimeters.





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EfficientMax™	MegaBuck™	SmartMax™	TinyWire™
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F-PFS™	PowerXS™		

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Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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